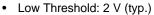


## 2SK1589-T1B-A-VB Datasheet N-Channel 100-V (D-S) MOSFET

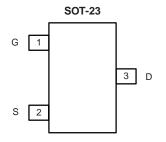
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (mA)		
100	2.8 at V <sub>GS</sub> = 10 V	260		

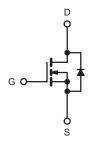
#### **FEATURES**

Halogen-free According to IEC 61249-2-21 Definition



- Low Input Capacitance: 25 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
   TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Durin Courset /T 450 °C)b	T <sub>A</sub> = 25 °C	I-	260		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 100 °C	- I <sub>D</sub>	150	mA	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	800		
Down Biotication	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.37	W	
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 100 °C	' D	0.15	VV	
Maximum Junction-to-Ambient <sup>b</sup>		R <sub>thJA</sub>	350	°C/W	
Operating Junction and Storage Temperature Range		T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C	

#### Notes:

- a. Pulse width limited by maximum junction temperature.b. Surface Mounted on FR4 board.



				Limits			
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			•			•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_D = 10  \mu\text{A}$ 100				V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1		2.5	V	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	±		± 10		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 15 \text{ V}$			1	μA	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 10 V			± 150	nA	
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 10 V, T <sub>J</sub> = 85 °C			± 1000		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100		
Zana Cata Valta na Duain Commant	,	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0 V , T <sub>J</sub> = 125 °C			500 µ		
On-State Drain Current <sup>a</sup>		V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 7.5 V	500			^	
	I <sub>D(on)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V	300			mA	
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 200 \text{ mA}$	2.8			Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 150 \text{ mA}$	3.0				
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 100 mA	100			mS	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 100 mA, V <sub>GS</sub> = 0 V			1.3	V	
Dynamic <sup>a</sup>			1		•		
Total Gate Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_{D} \cong 150 \text{ mA}$		0.5		nC	
Input Capacitance	C <sub>iss</sub>			30		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$		7			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		2.0			
Switching <sup>a, b, c</sup>	1	'					
Turn-On Time	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V}, R_1 = 150 \Omega$			20	T	
Turn-Off Time	t <sub>d(off)</sub>	$I_D \cong 200 \text{ mA}, V_{GEN} = 10 \text{ V}, R_G = 10 \Omega$			30	ns	

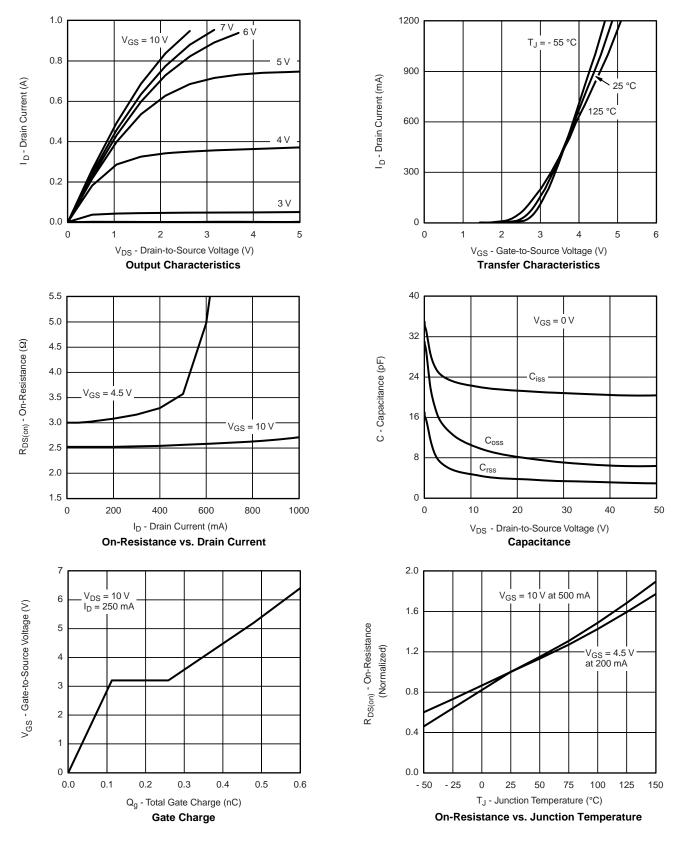
#### Notes:

- a. For DESIGN AID ONLY, not subject to production testing.
- b. Pulse test: PW  $\leq 300~\mu s$  duty cycle  $\leq 2~\%.$
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

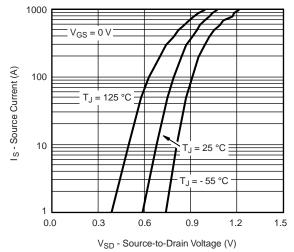


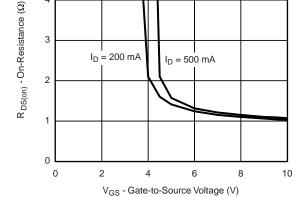
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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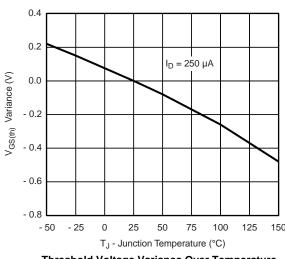


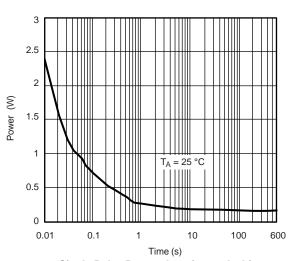


#### Source-Drain Diode Forward Voltage



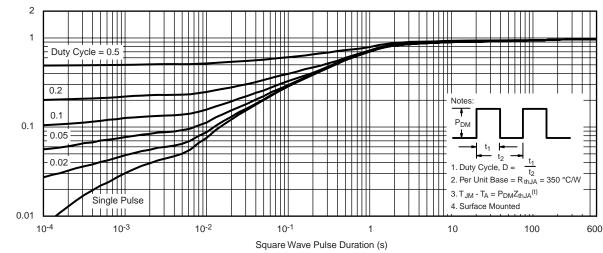
On-Resistance vs. Gate-Source Voltage





### **Threshold Voltage Variance Over Temperature**

Single Pulse Power, Junction-to-Ambient

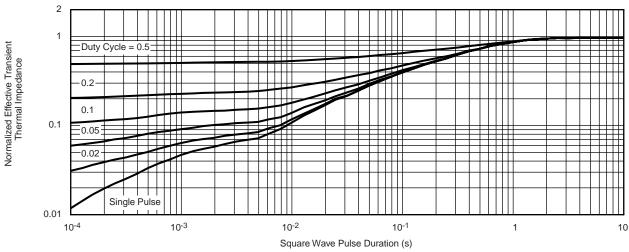


Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Effective Transient Thermal Impedance



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



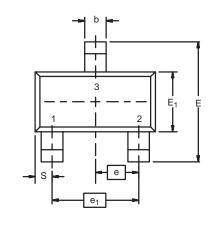
#### Normalized Thermal Transient Impedance, Junction-to-Foot

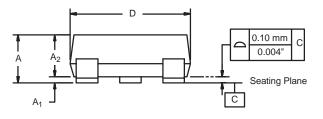
#### Note

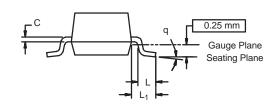
- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



## SOT-23 (TO-236): 3-LEAD





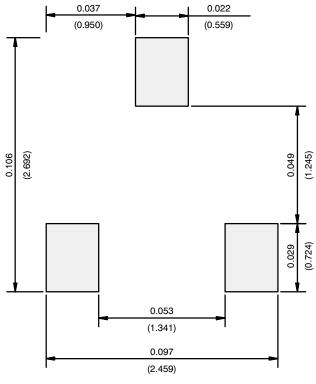


Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01	•	<u> </u>		

DWG: 5479



### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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